



SOD113A

plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220F "full pack"

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-220F
Package type industry code	TO-220F
Package style descriptive code	SFM (single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	2 LEADS TO220F
Mounting method type	H (heatsink mount)
Issue date	14-1-2014

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.2	-	15.5	15.8	mm
E	package width	9.7	-	10	10.3	mm
A	seated height	4	-	4.3	4.6	mm
e	nominal pitch	-	-	5.08	-	mm
n ₂	actual quantity of termination	-	-	2	-	

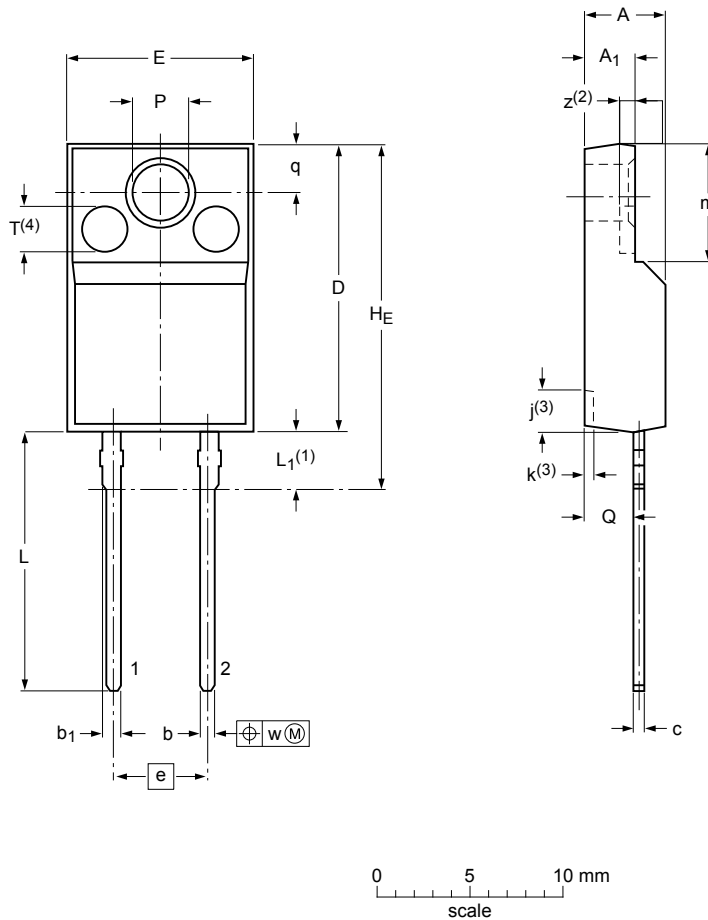


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2. Package outline

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Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	b ₁	c	D	E	e	H _{HE} max	j ⁽³⁾	k ⁽³⁾	L	L ₁ ⁽¹⁾	m	P	Q	q	T ⁽⁴⁾	W	z ⁽²⁾	
mm	max	4.6	3.1	0.9	1.1	0.7	15.8	10.3		2.7	0.8	14.4	3.3	6.5	3.2	2.8		2.6	2.55	0.4	0.8
	nom							5.08	19.0												
	min	4.0	2.5	0.7	0.9	0.4	15.2	9.7		1.7	0.4	13.5	2.8	6.3	3.0	2.3					

Note

1. Terminals are uncontrolled within zone L1.
2. z is depth of T.
3. Dot lines area designs may vary.
4. Eject pin mark is for reference only.

sod113a_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD113A	2 LEADS TO220F				14-01-14 14-04-10

Fig. 1. Package outline TO-220F (SOD113A)

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3. Legal information

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